# imall

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# Contact us

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# Panasonic

Zener Diode

## DZ2J130×0L Silicon epitaxial planar type

#### For constant voltage / For surge absorption circuit

- Features
- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: SJ or SU

#### Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C								
Parameter	Symbol	Rating	Unit					
Repetitive peak forward current	IFRM	200	mA					
Total power dissipation <sup>*1</sup>	PT	200	mW					
Electrostatic discharge <sup>*2</sup>	ESD	±8	kV					
Junction temperature	Tj	150	°C					
Operating ambient temperature	Topr	-40 to +85	°C					
Storage temperature	Tstg	-55 to +150	°C					

 
 Storage temperature
 Tstg
 -55 to
 +150
 °C

 Note)
 \*1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm) Solder in (Recommended land pattern)
 Solder in (Recommended land pattern)

\*2 Test method : IEC61000\_4\_2

(C = 150 pF, R = 330  $\Omega$ , Contact discharge : 10 times )

#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage <sup>*1, *2</sup>	VZ	IZ = 5 mA	12.40		13.65	V
Zener operating resistance	RZ	IZ = 5 mA			35	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω
Reverse current	IR	VR = 10 V			0.05	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		10.9		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

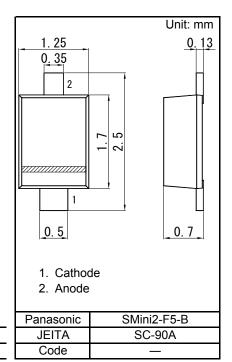
3. \*1 The temperature must be controlled 25 °C for VZ mesurement.

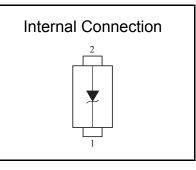
VZ value measured at other temperature must be adjusted to VZ (25 °C).

\*2 VZ guaranted 20 ms after current flow Rank classification

\*3 Tj = 25 °C to 150 °C

k classification								
Code M			0					
Rank	М		No-rank					
VZ	12.74	to 13.40	12.40	to 13.65				
Marking symbol	SU		SJ					

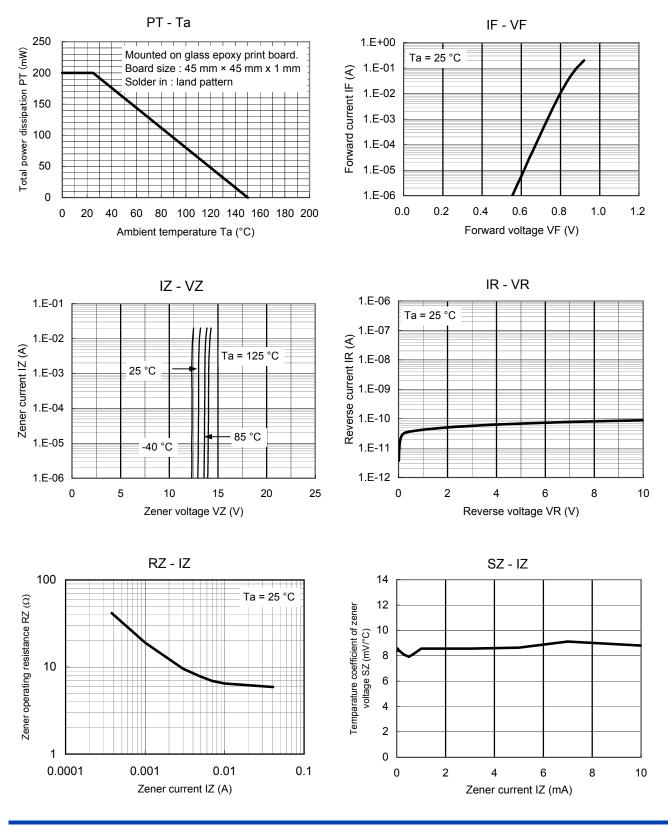






Zener Diode DZ2J130×0L

### Technical Data (reference)



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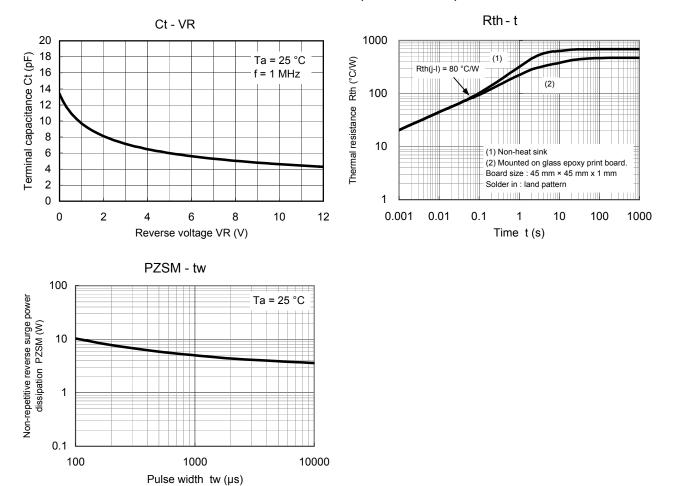
Established : 2009-10-14 Revised : 2013-07-12

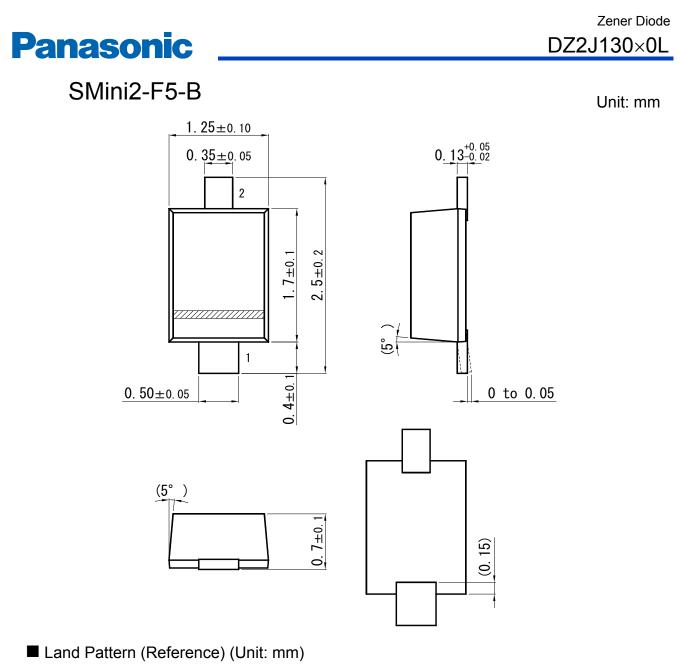


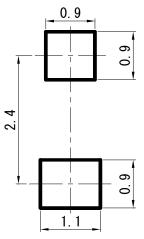


Zener Diode DZ2J130×0L

Technical Data (reference)







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